



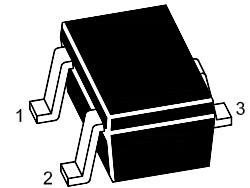
# PJM7002KNSI

## N-Channel Enhancement Mode Power MOSFET

### Features

- High density cell design for low  $R_{DS(on)}$
- Voltage controlled small signal switching
- High saturation current capability
- ESD protected(HBM) up to 2.5KV
- $V_{DS} = 60V, I_D = 0.34A$
- $R_{DS(on)} < 5\Omega @ V_{GS} = 10V$

SOT-323



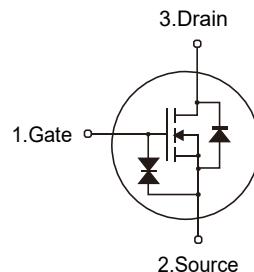
1. Gate 2. Source 3. Drain

Marking Code: 72K

### Applications

- DC/DC Converter
- Load Switch for Portable Devices

Schematic Diagram



### Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	0.34	A
Drain Current-Pulsed <sup>Note1</sup>	$I_{DM}$	0.8	A
Maximum Power Dissipation	$P_D$	0.2	W
Junction Temperature	$T_J$	150	°C
Storage Temperature Range	$T_{STG}$	-55 to +150	°C

### Thermal Characteristics

Thermal Resistance, Junction-to-Ambient <sup>Note2</sup>	$R_{\theta JA}$	625	°C/W
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# PJM7002KNSI

## N-Channel Enhancement Mode Power MOSFET

### Electrical Characteristics

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V	--	--	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±10	μA
Gate Threshold Voltage <sup>Note3</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.4	2.5	V
Drain-Source On-Resistance <sup>Note3</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A	--	1.3	5	Ω
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.2A	--	1.4	5.3	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz	--	--	40	pF
Output Capacitance	C <sub>oss</sub>		--	--	30	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		--	--	10	pF
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> =10 V, V <sub>DD</sub> =50V, R <sub>G</sub> =50Ω R <sub>GS</sub> =50Ω, R <sub>L</sub> =250Ω	--	--	10	nS
Turn-off Delay Time	t <sub>d(off)</sub>		--	--	15	nS
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =300mA, V <sub>R</sub> =25V, dI <sub>S</sub> /dt=-100A/μS	--	30	--	nS
Recovered Charge	Q <sub>r</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =300mA, V <sub>R</sub> =25V, dI <sub>S</sub> /dt=-100A/μS	--	30	--	nC
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =0.3A	--	--	1.5	V
Diode Forward Current <sup>Note2</sup>	I <sub>S</sub>		--	--	0.2	A

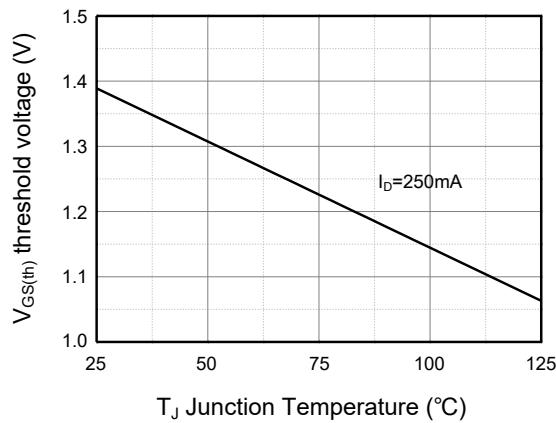
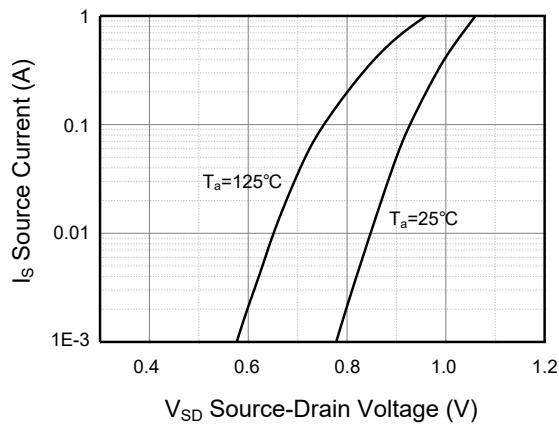
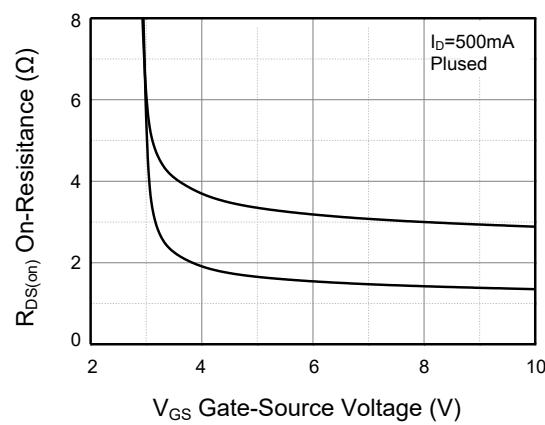
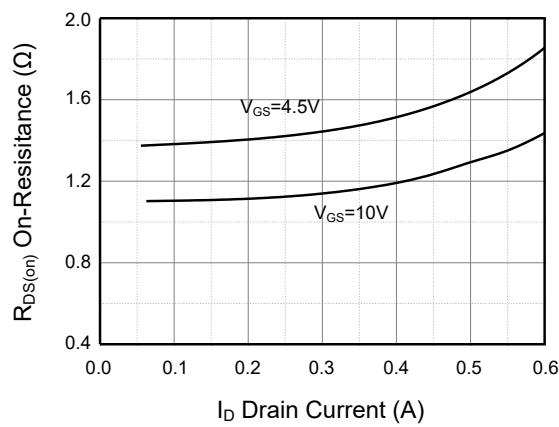
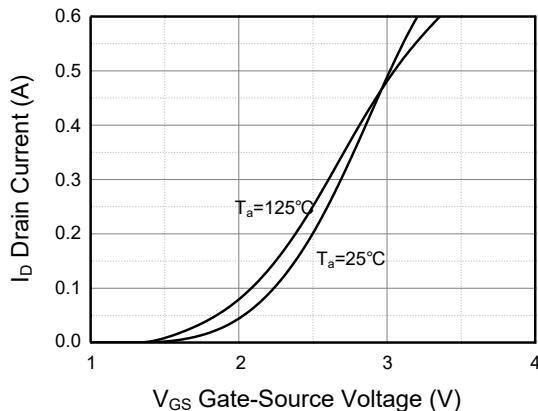
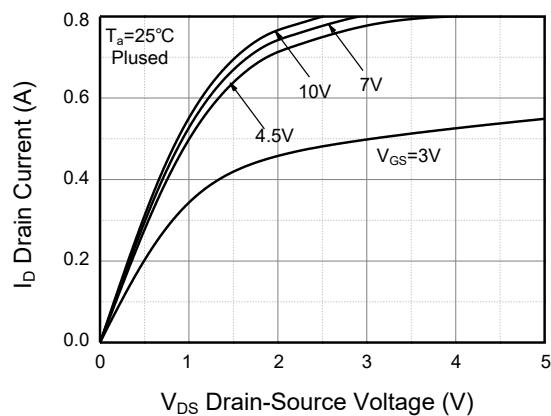
Note: 1. Repetitive rating: Pulse width limited by junction temperature.

2. Surface Mounted on FR4 Board, t ≤ 10 sec.

3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.



### Typical Characteristic Curves

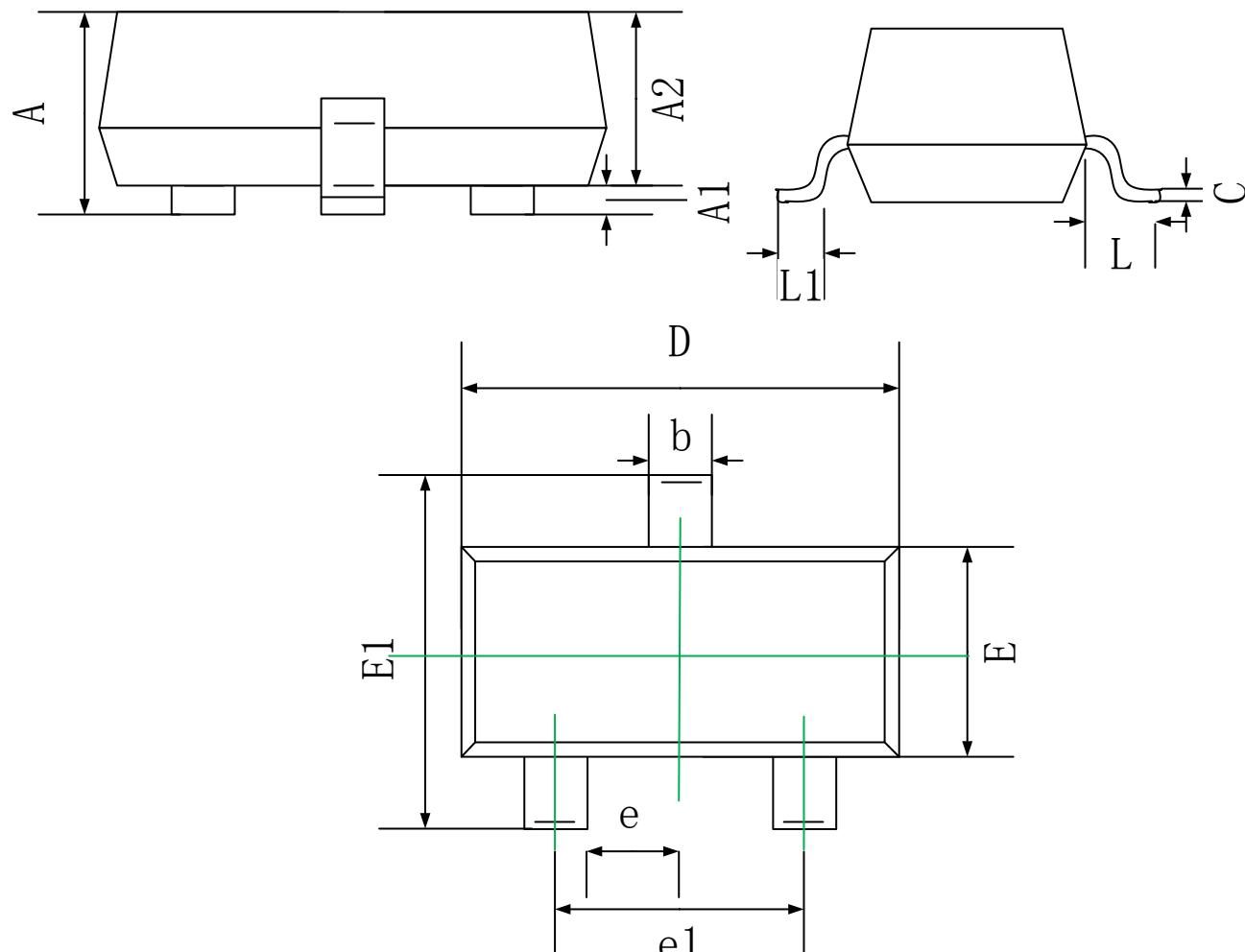




## Package Outline

SOT-323

Dimensions in mm



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	0.90	1.10
A1	0.00	0.10
A2	0.90	1.00
b	0.30	0.50
c	0.10	0.15
D	2.00	2.20
E	1.15	1.35
E1	2.15	2.40
e	0.65 TYP.	
e1	1.20	1.40
L	0.525 REF.	
L1	0.26	0.46